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Docket No. 10544-US-PA
Application No.: 10/709,179**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Chang et al.
Application No. : 10/709,179
Filed : April 19, 2004
For : STACK-TYPE MULTI-CHIP PACKAGE AND METHOD
OF FABRICATING BUMPS ON THE BACKSIDE OF A
CHIP
Art Unit : 2814
Examiner : HA, NATHAN W.

TRANSMITTAL LETTER**+1-571-273-8300**
(Via fax: 1+14 pages)

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In response to the Notice of Appeal filed on February 13, 2006, please find the *Appeal Brief* in 14 pages.

Please charge the payment in the amount of US\$500 to account No. 50-2620 (Order No.: 10544-US-PA) to cover the fee set forth in 37 CFR 1.17(c) for filing an Appeal Brief.

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Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

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Appeal Brief

3. The prior art differentiated

Similar to Ono, Koh also fails to teach or suggest forming at least a bump pad on the backside of the chip and forming a bump on the bump pad.

4. Even if combining Ono and Koh

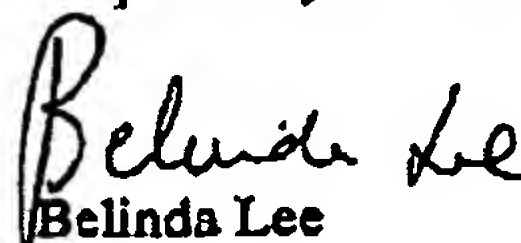
Since neither Ono nor Koh teaches or suggests at least forming at least a bump pad on the backside of the chip and forming a bump on the bump pad, Applicants respectfully submit that claim 15 defines over the prior art references for at least the reasons discussed above. If the independent claim 15 is allowable over the cited references, its dependent claim 20 is allowable as a matter of law, because the dependent claim contains all features of their respective independent claim 15. Accordingly, Ono and Koh, neither alone nor in combination can not possibly render the method of fabricating bumps on a backside of a chip of the claimed invention obvious.

P. Conclusion

As noted, the Examiner has not properly applied 35 U.S.C. § 102 and U.S.C. § 103 in his rejections of the claims at issue. Accordingly, Applicants believe that the rejections under 35 U.S.C. § 102 and U.S.C. § 103 to be in error, and respectfully request the Board of Appeals and interferences to reverse the Examiner's rejections of the claims on appeal.

Date: April 13, 2006

Respectfully Submitted,


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